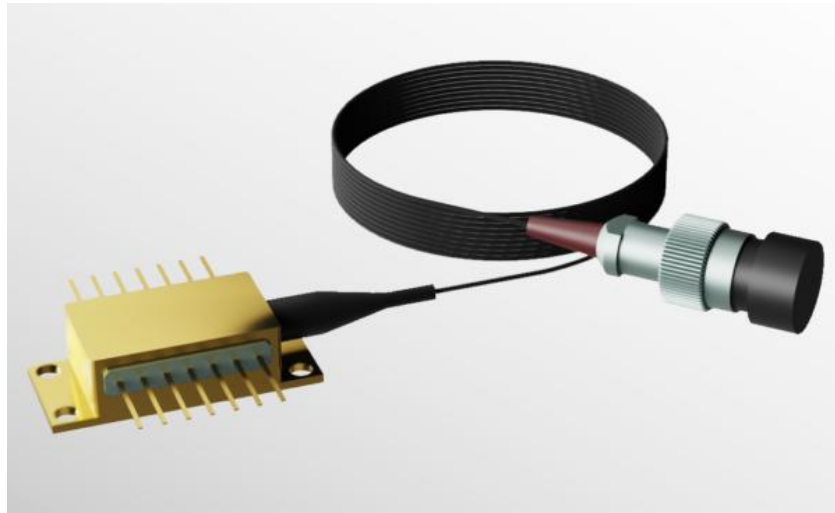


800nm DBR Laser Diode



● Product Description

The 800 nm Distributed Bragg Reflector (DBR) high-performance edge-emitting laser diode is fabricated based on advanced monolithic integrated single-frequency Gallium Arsenide (GaAs) laser technology. This series of diodes outputs single spatial mode laser beams, with passivated facet design to guarantee operational reliability. The 800 nm DBR device can serve as a low-noise pumping source, and is applicable to biomedical diagnosis and imaging fields.



● Product features

Excellent spectral performance ; High output power and outstanding operational reliability; Intelligent control and user-friendly usability

● Part Number

MP-DBR-800-130-14BF-PA

● Application area

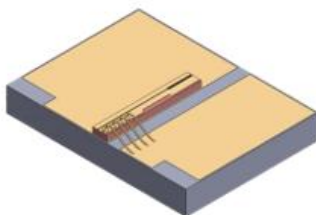
High-end Pumping Applications | Precision Sensing & Measurement Applications

● Core parameters

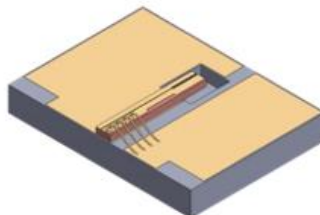
| Central Wavelength |
|--------------------|
| 800nm |

● General Parameters

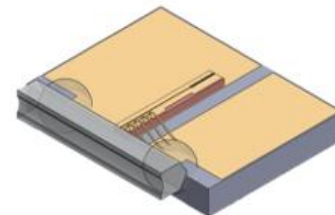
Detailed parameters



Chip on Submount (CoS)



CoS + Mode-Hop Free (MHF)



CoS + Virtual Point Source (VPS) Lens

800nm DBR chip carrier package (CoS) characteristics

| | Chip structure |
|---|----------------|
| Parameter ¹ | High power |
| Nominal wavelength (nm) ² | 800 ± 0.6 |
| Power range | 80-180 |
| Maximum Operating Current (CW & Pulse) (mA) | 250 |
| Maximum Operating Current Hour Power (mW) | 180 |
| Nominal Slope Efficiency (W/A) | 0.9 |
| Nominal threshold current (mA) | 60 |

1. Unless otherwise stated, all characteristics are measured at a case temperature (TC) of 25°C. Operating outside of these parameters will void the warranty.
2. A chip carrier (CoS) may be included in a sealed package with a wavelength deviation of ±1.2 nm from the nominal value

Available free-space encapsulation add-ons



TO-8



C-Mount



Transmitter Optical Subassembly (TOSA)

Parameters

Laser

| Parameters | unit | Minimum | Typical values | Maximum |
|--|------------|---------|----------------|---------|
| Storage temperature | °C | 0 | - | 70 |
| Shell operating temperature | °C | 5 | - | 70 |
| The laser chip operating temperature ¹ | °C | 5 | - | 45 |
| Laser series resistance | Ω | - | 2 | - |
| Laser forward voltage @LIV current | V | - | 2 | - |
| Laser line width, typical @LIV current | kHz | - | 500 | - |
| Beam Divergence Angle @FWHM ($\theta_{ }$ x θ_{\perp}) | ° | - | 6x28 | 8 x 32 |
| Edge-mode rejection ratio (SMSR) | dB | - | -40 | - |
| Polarization extinction ratio | dB | -17 | -20 | - |
| Polarized state of the laser | TE | | | |
| Pattern structure | Basic mode | | | |
| Temperature tuning rate | nm/°C | - | 0.06 | - |
| Current tuning rate | nm/mA | - | 0.002 | - |
| Laser reverse voltage | V | - | - | 0 |

1. If the package is not sealed, it is not recommended to work in an environment below the dew point



Free-space Package add-ons

| Parameters | unit | Minimum | Typical values | Maximum |
|----------------------------|------------|---------|----------------|---------|
| Photodiode forward current | mA | - | - | 10 |
| Photodiode reverse voltage | V | - | - | 50 |
| TEC Current (TOSA) | A | -1.1 | - | 1.1 |
| TEC Voltage (TOSA) | V | -3.0 | - | 3.0 |
| TEC Current (TO-8) | A | -1.8 | - | 1.8 |
| TEC Voltage (TO-8) | V | -2.2 | - | 2.2 |
| Thermistors | k Ω | - | 10 | - |

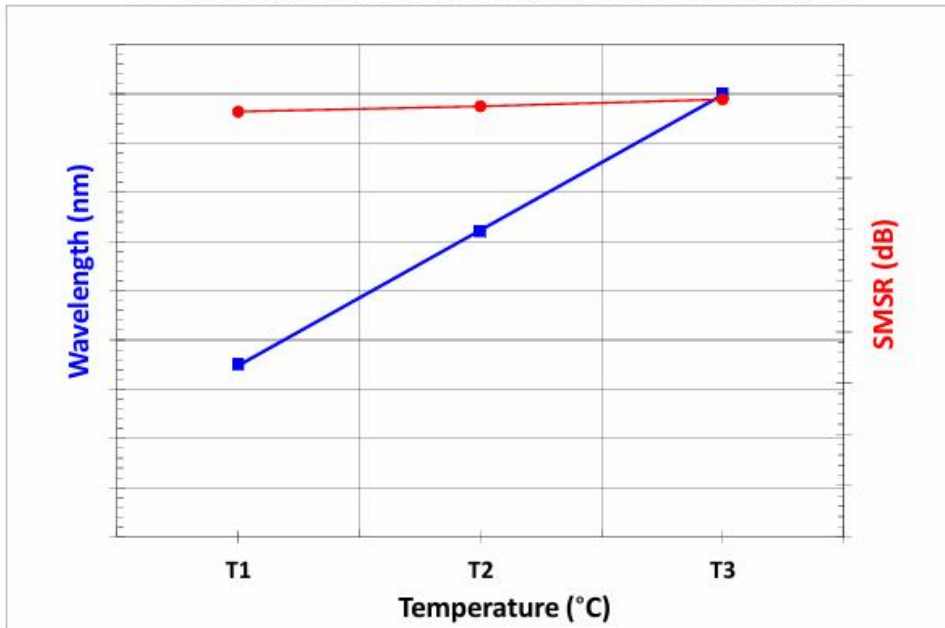
Handling Precautions

These devices are sensitive to ESD. When handling the module, grounded work area and wrist strap must be used. Always store in an antistatic container with all leads shorted together.





Air Wavelength Characteristics at Constant Current by Temperature



LIV Characteristics by Current

